

# COPY

FORM HDP-1449 (Based on Form PTO-1449)  <b>PATENT AND TRADEMARK OFFICE</b> <b>INFORMATION DISCLOSURE CITATION</b> (Use several sheets if necessary)		ATTORNEY DOCKET No. 6550-000013/COA	SERIAL No. 10/730,398
<div style="display: flex; align-items: center; justify-content: center;"> <div style="border: 1px solid black; border-radius: 50%; padding: 10px; margin-right: 10px; text-align: center;">             DEC 12 2006              PATENT &amp; TRADEMARK OFFICE           </div> <div>             Sheet 1 of 3           </div> </div>		APPLICANT Biehler, et al.	
		FILING DATE 12/8/2003	GROUP 1742

U.S. PATENT DOCUMENTS						
Ref. Desig.	Examiner's Initials	Document Number	Date	Name	Class/ Subclass	(If appropriate) Filing Date
1.	✓	3,481,795*	12/1969	Lane		
2.		4,248,905*	02/1981	Harvey		
3.		4,358,884*	11/1982	Harvey et al.		
4.		4,506,822*	3/1985	Hammersand et al.		
5.		5,066,544*	11/1991	Betrabet et al.		
6.		5,094,700*	3/1992	Sekhar		
7.		5,344,607*	9/1994	Gonya et al.		
8.		5,429,689*	7/1995	Shangguan et al.		
9.	✓	5,527,628*	6/1996	Anderson et al.		

\* Previously submitted in an IDS in parent application.

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)		
Ref. Desig.	Examiner's Initials	
1.	✓	Anderson, et al., "Microstructural Modifications and Properties of Sn-Ag-Cu Solder Joints Induced By Alloying", Journal of Electronic Materials, vol. 31, no. 11, pp. 1166-1174 (2002)
2.	✓	Attarwala, A.I. et al., "Confirmation of Creep and Fatigue Damage in Pb/Sn Solder Joints," J. Electron. Packag. 114:109-111 (1992)*
3.	✓	Betrabet, H.S. et al., "Processing Dispersion-Strengthened Sn-Pb Solders To Achieve Microstructural Refinement And Stability," Script Metall. 25:2323-2328 (1991)*
4.	✓	Betrabet, H.S. et al., "Towards Increased Fatigue Resistance In Sn-Pb Solders By Dispersion Strengthening," Proc. Conf. NEPCON., West Anaheim, CA, pp. 1276-1277 (1992)*
5.	✓	Clough, R.B. et al., "Preparation And Properties Of Reflowed Paste And Bulk Composite Solder," Proc. Conf. NEPCON., West Anaheim, CA, pp. 1256-1265 (1992)*
6.	✓	Frear, D.R. et al., "Thermal Fatigue In Solder Joints," JOM, pgs. 18-22 (June, 1988)*

Examiner: <u>S. Iq</u>	Date Considered: <u>3/5/07</u>
------------------------	--------------------------------

EXAMINER: Please initial if citation considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.